

# LNPT<sup>TM</sup> THERMOCOMP<sup>TM</sup> COMPOUND LC00APXQ

LC00APXQ

## DESCRIPTION

LNP THERMOCOMP LC00APXQ compound is based on Polyetheretherketone (PEEK) resin containing 50% carbon fiber. Added features of this grade include: Exceptional Processing, Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, High Flow, Carbon fiber filled, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding
INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, brk, Type I, 5 mm/min	328	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	1.2	%	ASTM D638
Tensile Modulus, 5 mm/min	49800	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	505	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	40500	MPa	ASTM D790
Tensile Stress, break, 5 mm/min	320	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.1	%	ISO 527
Tensile Modulus, 1 mm/min	47400	MPa	ISO 527
Flexural Stress	473	MPa	ISO 178
Flexural Modulus, 2 mm/min	40730	MPa	ISO 178
Shear Modulus	5187	MPa	ASTM D732
Shear Strength	114	MPa	ASTM D732
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched, 23°C	768	J/m	ASTM D4812
Izod Impact, notched, 23°C	77	J/m	ASTM D256
Instrumented Dart Impact Total Energy, 23°C	7	J	ASTM D3763
<b>THERMAL <sup>(1)</sup></b>			
HDT, 1.82 MPa, 3.2mm, unannealed	335	°C	ASTM D648
CTE, -40°C to 150°C, flow	2.E-06	1/°C	ASTM E831
CTE, -40°C to 150°C, xflow	2.E-05	1/°C	ASTM E831
<b>PHYSICAL <sup>(1)</sup></b>			

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Specific Gravity	1.48	-	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.03	%	ASTM D570
Mold Shrinkage, flow, 24 hrs <sup>(2)</sup>	0.13 – 0.25	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs <sup>(2)</sup>	0.6 – 1.3	%	ASTM D955
Poisson's Ratio	0.45	-	ASTM E132
<b>ELECTRICAL <sup>(1)</sup></b>			
Surface Resistivity	1.E+02 – 1.E+03	Ω	ASTM D257
<b>INJECTION MOLDING <sup>(3)</sup></b>			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Front - Zone 3 Temperature	380 – 400	°C	
Middle - Zone 2 Temperature	380 – 400	°C	
Rear - Zone 1 Temperature	370 – 380	°C	
Mold Temperature	175 – 190	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.